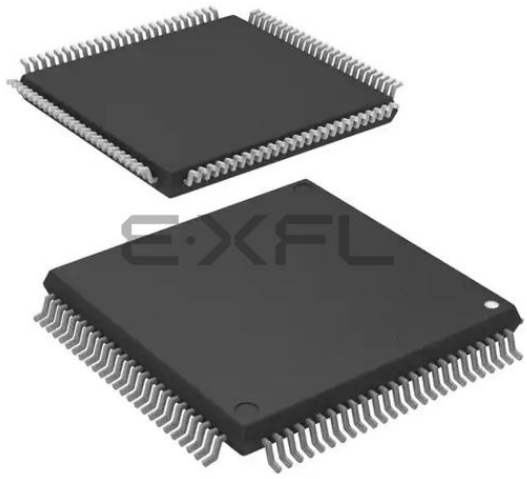
Renesas Electronics America Inc - R5F562T7DDFP#V3 Datasheet



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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Discontinued at Digi-Key
Core Processor	RX
Core Size	32-Bit Single-Core
Speed	100MHz
Connectivity	I²C, LINbus, SCI, SPI
Peripherals	DMA, LVD, POR, PWM, WDT
Number of I/O	55
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	4V ~ 5.5V
Data Converters	A/D 12x10b, 8x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	100-LFQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f562t7ddfp-v3

Table 1.1 Outline of Specifications (2 / 5)

Classification	Module/Function	Description
Interrupt	Interrupt controller (ICU)	• Peripheral function interrupts: 101 sources • External interrupts: 9 (NMI and IRQ0 to IRQ7 pins) • Non-maskable interrupts: 3 (the NMI pin, oscillation stop detection interrupt, and voltage-monitoring interrupt) • 16 levels specifiable for the order of priority
Data transfer	Data transfer controller (DTC)	• Three transfer modes: Normal transfer, repeat transfer, and block transfer • Activation sources: Software trigger, external interrupts, and interrupt requests from peripheral functions
I/O ports	Programmable I/O ports	I/O port pins for devices in the 112-pin LQFP/100-pin LQFP/ 80-pin LQFP (R5F562TxGDFF)/80-pin LQFP (except R5F562TxGDFF)/64-pin LQFP • I/O: 61/55/44/44/37 • Input only: 21/21/13/13/9 • Open-drain outputs: 2/2/2/2/2 (I^2C bus interface pins) • Large-current outputs: 12/12/12/6/6(0) (MTU3 and GPT pins) The 5-V version of the 64-pin product does not have large-current outputs. • Reading out the states of pins is always possible.
Timers	Multi-function timer pulse unit 3 (MTU3)	• 16 bits x 8 channels • Up to 24 pulse inputs/outputs and three pulse inputs • Select from among six to eight counter-input clock signals for each channel (ICLK/1, ICLK/4, ICLK/16, ICLK/64, ICLK/256, ICLK/1024, MTCLKA, MTCLKB, MTCLKC, MTCLKD) other than channel 5, for which only four signals are available. • 24 output compare or input capture registers • Counter clearing (clearing is synchronizable with compare match or input capture) • Simultaneous writing to multiple timer counters (TCNT) • Input to and output from all registers in synchronization with counter operation • Buffered operation • Cascade-connected operation • 38 kinds of interrupt source • Automatic transfer of register data • Pulse output modes Toggled, PWM, complementary PWM, and reset synchronous PWM • Complementary PWM output mode Outputs non-overlapping waveforms for controlling 3-phase inverters Automatic specification of dead times PWM duty cycle: Selectable as any value from 0% to 100% Delay can be applied to requests for A/D conversion. Non-generation of interrupt requests at peak or trough values of counters can be selected. Double buffering • Reset-synchronous PWM mode Three PWM waveforms and corresponding inverse waveforms are output with the desired duty cycles. • Phase-counting mode • Counter functionality for dead-time compensation • Generation of triggers for A/D converters • Differential timing for initiation of A/D conversion
	Port output enable 3 (POE3)	• Control of the high-impedance state of the MTU3 and GPT's waveform output pins 5 pins for input from signal sources: POE0, POE4, POE8, POE10, POE11 Initiation on detection of short-circuited outputs (detection of simultaneous switching of large-current pins to the active level) Initiation by comparator-detection of analog level input to the 12-bit A/D converter Initiation by oscillation-stoppage detection Initiation by software • Selection of which output pins should be placed in the high-impedance state at the time of each POE input or comparator detection

Table 1.5 List of Pins and Pin Functions (100-Pin LQFP) (2 / 3)

Pin No. (80-Pin LQFP)	Power Supply Clock System Control	I/O Port	Analog	Timer	Communi-cation	Interrupt	POE	Debugging
41		PA0		MTIOC6C	SSL3-B			
42	VCC							
43		P96				IRQ4	POE4#	
44	VSS							
45		P95		MTIOC6B				
46		P94		MTIOC7A				
47		P93		MTIOC7B				
48		P92		MTIOC6D				
49		P91		MTIOC7C				
50		P90		MTIOC7D				
51		P76		MTIOC4D/ GTIOC2B-A				
52		P75		MTIOC4C/ GTIOC1B-A				
53		P74		MTIOC3D/ GTIOC0B-A				
54		P73		MTIOC4B/ GTIOC2A-A				
55		P72		MTIOC4A/ GTIOC1A-A				
56		P71		MTIOC3B/ GTIOC0A-A				
57		P70				IRQ5	POE0#	
58		P33		MTIOC3A/ MTCLKA-A	SSL3-A			
59		P32		MTIOC3C/ MTCLKB-A	SSL2-A			
60	VCC							
61		P31		MTIOC0A-B/ MTCLKC-A	SSL1-A			
62	VSS							
63		P30		MTIOC0B-B/ MTCLKD-A	SSL0-A			
64		P24			RSPCK-A			
65		P23			CTX-B/ LTX/ MOSI-A			
66		P22	ADTRG#		CRX-B/ LRX/ MISO-A			
67		P21	ADTRG1#-B	MTCLKA-B		IRQ6		
68		P20	ADTRG0#-B	MTCLKB-B		IRQ7		
69		P65	AN5					
70		P64	AN4					
71	AVCC							
72	VREF							
73	AVSS							
74		P63	AN3					
75		P62	AN2					
76		P61	AN1					

4. I/O Registers

This section gives information on the on-chip I/O register addresses and bit configurations. The information is given as shown below. Notes on writing to registers are also given at the end.

(1) I/O register addresses (address order)

- Registers are listed from the lower allocation addresses.
- Registers are classified according to functional modules (abbreviations).
- The number of access cycles indicates the number of states based on the specified reference clock.
- Among the I/O register area, addresses not listed in the list of registers are reserved. Reserved addresses must not be accessed. Do not access these addresses; otherwise, the operation when accessing these bits and subsequent operations cannot be guaranteed.
- A unit of access is specified for each register. Access other than in the specified unit is prohibited.

(2) I/O register bits

- Bit configurations of the registers are listed in the same order as the register addresses.
- Reserved bits are indicated by "—" in the bit name column.
- Space in the bit name field indicates that the entire register is allocated to either the counter or data.
- For the registers of 16 or 32 bits, the MSB is listed first.

(3) Notes on writing to I/O registers

When writing to an I/O register, the CPU starts executing the subsequent instruction before completing I/O register write. This may cause the subsequent instruction to be executed before the post-update I/O register value is reflected on the operation.
As described in the following examples, special care is required for the cases in which the subsequent instruction must be executed after the post-update I/O register value is actually reflected.

[Examples of cases requiring special care]

- The subsequent instruction must be executed while an interrupt request is disabled with the IENj bit in IERm of the ICU (interrupt request enable bit)*1 cleared to 0.
- A WAIT instruction is executed immediately after the preprocessing for causing a transition to the low power consumption state.

Note 1. See section 11.2.2, Interrupt Request Enable Register m (IERm) (m = 02h to 1Fh) in the User's manual: Hardware.

In the above cases, after writing to an I/O register, wait until the write operation is completed using the following procedure and then execute the subsequent instruction.

Table 4.1 List of I/O Registers (Address Order) (11 / 25)

Address	Module Abbreviation	Register Name	Register Abbreviation	Number of Bits	Access Size	Number of Access Cycles
0008 8383h	RSPI	RSPI status register	SPSR	8	8	2, 3 PCLK*3
0008 8384h	RSPI	RSPI data register	SPDR	16, 32	16, 32	2, 3 PCLK*3
0008 8388h	RSPI	RSPI sequence control register	SPSCR	8	8	2, 3 PCLK*3
0008 8389h	RSPI	RSPI sequence status register	SPSSR	8	8	2, 3 PCLK*3
0008 838Ah	RSPI	RSPI bit rate register	SPBR	8	8	2, 3 PCLK*3
0008 838Bh	RSPI	RSPI data control register	SPDCR	8	8	2, 3 PCLK*3
0008 838Ch	RSPI	RSPI clock delay register	SPCKD	8	8	2, 3 PCLK*3
0008 838Dh	RSPI	RSPI slave select negation delay register	SSLND	8	8	2, 3 PCLK*3
0008 838Eh	RSPI	RSPI next-access delay register	SPND	8	8	2, 3 PCLK*3
0008 838Fh	RSPI	RSPI control register 2	SPCR2	8	8	2, 3 PCLK*3
0008 8390h	RSPI	RSPI command register 0	SPCMD0	16	16	2, 3 PCLK*3
0008 8392h	RSPI	RSPI command register 1	SPCMD1	16	16	2, 3 PCLK*3
0008 8394h	RSPI	RSPI command register 2	SPCMD2	16	16	2, 3 PCLK*3
0008 8396h	RSPI	RSPI command register 3	SPCMD3	16	16	2, 3 PCLK*3
0008 8398h	RSPI	RSPI command register 4	SPCMD4	16	16	2, 3 PCLK*3
0008 839Ah	RSPI	RSPI command register 5	SPCMD5	16	16	2, 3 PCLK*3
0008 839Ch	RSPI	RSPI command register 6	SPCMD6	16	16	2, 3 PCLK*3
0008 839Eh	RSPI	RSPI command register 7	SPCMD7	16	16	2, 3 PCLK*3
0008 9000h	S12AD0	A/D control register	ADCSR	8	8	2, 3 PCLK*3
0008 9004h	S12AD0	A/D channel select register	ADANS	16	16	2, 3 PCLK*3
0008 900Ah	S12AD0	A/D programmable gain amplifier register	ADPG	16	16	2, 3 PCLK*3
0008 900Eh	S12AD0	A/D control extended register	ADCER	16	16	2, 3 PCLK*3
0008 9010h	S12AD0	A/D start trigger select register	ADSTRGR	16	16	2, 3 PCLK*3
0008 9012h	S12AD	Comparator operating mode select register 0	ADCMPMD0	16	16	2, 3 PCLK*3
0008 9014h	S12AD	Comparator operating mode select register 1	ADCMPMD1	16	16	2, 3 PCLK*3
0008 9016h	S12AD	Comparator filter mode register 0	ADCMPNR0	16	16	2, 3 PCLK*3
0008 9018h	S12AD	Comparator filter mode register 1	ADCMPNR1	16	16	2, 3 PCLK*3
0008 901Ah	S12AD	Comparator detection flag register	ADCMPFR	8	8	2, 3 PCLK*3
0008 901Ch	S12AD	Comparator interrupt select register	ADCMPSEL	16	16	2, 3 PCLK*3
0008 901Eh	S12AD0	A/D data register Diag	ADRD	16	16	2, 3 PCLK*3
0008 9020h	S12AD0	A/D data register 0A	ADDR0A	16	16	2, 3 PCLK*3
0008 9022h	S12AD0	A/D data register 1	ADDR1	16	16	2, 3 PCLK*3
0008 9024h	S12AD0	A/D data register 2	ADDR2	16	16	2, 3 PCLK*3
0008 9026h	S12AD0	A/D data register 3	ADDR3	16	16	2, 3 PCLK*3
0008 9030h	S12AD0	A/D data register 0B	ADDR0B	16	16	2, 3 PCLK*3
0008 9060h	S12AD0	A/D sampling state register	ADSSTR	8	8	2, 3 PCLK*3
0008 9080h	S12AD1	A/D control register	ADCSR	8	8	2, 3 PCLK*3
0008 9084h	S12AD1	A/D channel select register	ADANS	16	16	2, 3 PCLK*3
0008 908Ah	S12AD1	A/D programmable gain amplifier register	ADPG	16	16	2, 3 PCLK*3
0008 908Eh	S12AD1	A/D control extended register	ADCER	16	16	2, 3 PCLK*3
0008 9090h	S12AD1	A/D start trigger select register	ADSTRGR	16	16	2, 3 PCLK*3
0008 909Eh	S12AD1	A/D data register Diag	ADRD	16	16	2, 3 PCLK*3
0008 90A0h	S12AD1	A/D data register 0A	ADDR0A	16	16	2, 3 PCLK*3
0008 90A2h	S12AD1	A/D data register 1	ADDR1	16	16	2, 3 PCLK*3

Table 4.2 List of I/O Registers (Bit Order) (2 / 30)

Module Abbreviation	Register Abbreviation	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
MPU	REPAGE0				REPN[27:0]				
					REPN[27:0]				
					REPN[27:0]				
			REPN[27:0]				UAC[2:0]		V
MPU	RSPAGE1				RSPN[27:0]				
					RSPN[27:0]				
					RSPN[27:0]				
			RSPN[27:0]			—	—	—	—
MPU	REPAGE1				REPN[27:0]				
					REPN[27:0]				
					REPN[27:0]				
			REPN[27:0]				UAC[2:0]		V
MPU	RSPAGE2				RSPN[27:0]				
					RSPN[27:0]				
					RSPN[27:0]				
			RSPN[27:0]			—	—	—	—
MPU	REPAGE2				REPN[27:0]				
					REPN[27:0]				
					REPN[27:0]				
			REPN[27:0]				UAC[2:0]		V
MPU	RSPAGE3				RSPN[27:0]				
					RSPN[27:0]				
					RSPN[27:0]				
			RSPN[27:0]			—	—	—	—
MPU	REPAGE3				REPN[27:0]				
					REPN[27:0]				
					REPN[27:0]				
			REPN[27:0]				UAC[2:0]		V
MPU	RSPAGE4				RSPN[27:0]				
					RSPN[27:0]				
					RSPN[27:0]				
			RSPN[27:0]			—	—	—	—
MPU	REPAGE4				REPN[27:0]				
					REPN[27:0]				
					REPN[27:0]				
			REPN[27:0]				UAC[2:0]		V
MPU	RSPAGE5				RSPN[27:0]				
					RSPN[27:0]				
					RSPN[27:0]				
			RSPN[27:0]			—	—	—	—
MPU	REPAGE5				REPN[27:0]				
					REPN[27:0]				
					REPN[27:0]				
			REPN[27:0]				UAC[2:0]		V
MPU	RSPAGE6				RSPN[27:0]				
					RSPN[27:0]				
					RSPN[27:0]				
			RSPN[27:0]			—	—	—	—
MPU	REPAGE6				REPN[27:0]				
					REPN[27:0]				
					REPN[27:0]				
			REPN[27:0]				UAC[2:0]		V

Table 4.2 List of I/O Registers (Bit Order) (6 / 30)

Module Abbreviation	Register Abbreviation	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
ICU	DTCER029	—	—	—	—	—	—	—	DTCE
ICU	DTCER030	—	—	—	—	—	—	—	DTCE
ICU	DTCER031	—	—	—	—	—	—	—	DTCE
ICU	DTCER045	—	—	—	—	—	—	—	DTCE
ICU	DTCER046	—	—	—	—	—	—	—	DTCE
ICU	DTCER064	—	—	—	—	—	—	—	DTCE
ICU	DTCER065	—	—	—	—	—	—	—	DTCE
ICU	DTCER066	—	—	—	—	—	—	—	DTCE
ICU	DTCER067	—	—	—	—	—	—	—	DTCE
ICU	DTCER068	—	—	—	—	—	—	—	DTCE
ICU	DTCER069	—	—	—	—	—	—	—	DTCE
ICU	DTCER070	—	—	—	—	—	—	—	DTCE
ICU	DTCER071	—	—	—	—	—	—	—	DTCE
ICU	DTCER098	—	—	—	—	—	—	—	DTCE
ICU	DTCER102	—	—	—	—	—	—	—	DTCE
ICU	DTCER103	—	—	—	—	—	—	—	DTCE
ICU	DTCER106	—	—	—	—	—	—	—	DTCE
ICU	DTCER114	—	—	—	—	—	—	—	DTCE
ICU	DTCER115	—	—	—	—	—	—	—	DTCE
ICU	DTCER116	—	—	—	—	—	—	—	DTCE
ICU	DTCER117	—	—	—	—	—	—	—	DTCE
ICU	DTCER121	—	—	—	—	—	—	—	DTCE
ICU	DTCER122	—	—	—	—	—	—	—	DTCE
ICU	DTCER125	—	—	—	—	—	—	—	DTCE
ICU	DTCER126	—	—	—	—	—	—	—	DTCE
ICU	DTCER129	—	—	—	—	—	—	—	DTCE
ICU	DTCER130	—	—	—	—	—	—	—	DTCE
ICU	DTCER131	—	—	—	—	—	—	—	DTCE
ICU	DTCER132	—	—	—	—	—	—	—	DTCE
ICU	DTCER134	—	—	—	—	—	—	—	DTCE
ICU	DTCER135	—	—	—	—	—	—	—	DTCE
ICU	DTCER136	—	—	—	—	—	—	—	DTCE
ICU	DTCER137	—	—	—	—	—	—	—	DTCE
ICU	DTCER138	—	—	—	—	—	—	—	DTCE
ICU	DTCER139	—	—	—	—	—	—	—	DTCE
ICU	DTCER140	—	—	—	—	—	—	—	DTCE
ICU	DTCER141	—	—	—	—	—	—	—	DTCE
ICU	DTCER142	—	—	—	—	—	—	—	DTCE
ICU	DTCER143	—	—	—	—	—	—	—	DTCE
ICU	DTCER144	—	—	—	—	—	—	—	DTCE
ICU	DTCER145	—	—	—	—	—	—	—	DTCE
ICU	DTCER149	—	—	—	—	—	—	—	DTCE
ICU	DTCER150	—	—	—	—	—	—	—	DTCE
ICU	DTCER151	—	—	—	—	—	—	—	DTCE
ICU	DTCER152	—	—	—	—	—	—	—	DTCE
ICU	DTCER153	—	—	—	—	—	—	—	DTCE
ICU	DTCER174	—	—	—	—	—	—	—	DTCE
ICU	DTCER175	—	—	—	—	—	—	—	DTCE
ICU	DTCER176	—	—	—	—	—	—	—	DTCE
ICU	DTCER177	—	—	—	—	—	—	—	DTCE
ICU	DTCER178	—	—	—	—	—	—	—	DTCE
ICU	DTCER179	—	—	—	—	—	—	—	DTCE

Table 4.2 List of I/O Registers (Bit Order) (11 / 30)

Module Abbreviation	Register Abbreviation	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
SCI1	SEMR	—	—	NFEN	ABCS	—	—	—	—
SMCI1	SMR	GM	BLK	PE	PM	(BCP[1:0])		CKS[1:0]	
SMCI1	BRR								
SMCI1	SCR	TIE	RIE	TE	RE	MPIE	TEIE	CKE[1:0]	
SMCI1	TDR								
SMCI1	SSR	TDRE	RDRF	ORER	ERS	PER	TEND	MPB	MPBT
SMCI1	RDR								
SMCI1	SCMR	BCP2	—	—	—	SDIR	SINV	—	SMIF
SCI2	SMR	CM	CHR	PE	PM	STOP	MP	CKS[1:0]	
SCI2	BRR								
SCI2	SCR	TIE	RIE	TE	RE	MPIE	TEIE	CKE[1:0]	
SCI2	TDR								
SCI2	SSR	TDRE	RDRF	ORER	FER	PER	TEND	MPB	MPBT
SCI2	RDR								
SCI2	SCMR	BCP2	—	—	—	SDIR	SINV	—	SMIF
SMCI2	SMR	GM	BLK	PE	PM	(BCP[1:0])		CKS[1:0]	
SMCI2	BRR								
SMCI2	SCR	TIE	RIE	TE	RE	MPIE	TEIE	CKE[1:0]	
SMCI2	TDR								
SMCI2	SSR	TDRE	RDRF	ORER	ERS	PER	TEND	MPB	MPBT
SMCI2	RDR								
SMCI2	SCMR	BCP2	—	—	—	SDIR	SINV	—	SMIF
CRC	CRCCR	DORCLR	—	—	—	—	LMS	GPS[1:0]	
CRC	CRCDIR								
CRC	CRCDOR								
RIIC0	ICCR1	ICE	IICRST	CLO	SOWP	SCLO	SDAO	SCLI	SDAI
RIIC0	ICCR2	BBSY	MST	TRS	—	SP	RS	ST	—
RIIC0	ICMR1	MTWP		CKS[2:0]		BCWP		BC[2:0]	
RIIC0	ICMR2	DLCS		SDDL[2:0]		TMWE	TMOH	TMOL	TMOS
RIIC0	ICMR3	SMBS	WAIT	RDRFS	ACKWP	ACKBT	ACKBR	NF[1:0]	
RIIC0	ICFER	—	SCLE	NFE	NACKE	SALE	NALE	MALE	TMOE
RIIC0	ICSER	HOAE	—	DIDE	—	GCAE	SAR2E	SAR1E	SAR0E
RIIC0	ICIER	TIE	TEIE	RIE	NAKIE	SPIE	STIE	ALIE	TMOIE
RIIC0	ICSR1	HOA	—	DID	—	GCA	AAS2	AAS1	AAS0
RIIC0	ICSR2	TDRE	TEND	RDRF	NACKF	STOP	START	AL	TMOF
RIIC0	SARL0				SVA[6:0]				SVA0
RIIC0	TMOCNTL								
RIIC0	SARU0	—	—	—	—	—		SVA[1:0]	FS
RIIC0	TMOCNTU								
RIIC0	SARL1				SVA[6:0]				SVA0
RIIC0	SARU1	—	—	—	—	—		SVA[1:0]	FS
RIIC0	SARL2				SVA[6:0]				SVA0
RIIC0	SARU2	—	—	—	—	—		SVA[1:0]	FS
RIIC0	ICBRL	—	—	—			BRL[4:0]		
RIIC0	ICBRH	—	—	—			BRH[4:0]		
RIIC0	ICDRT								
RIIC0	ICDRR								
RSPI0	SPCR	SPRIE	SPE	SPTIE	SPEIE	MSTR	MODFEN	TXMD	SPMS

Table 4.2 List of I/O Registers (Bit Order) (14 / 30)

Module Abbreviation	Register Abbreviation	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
PORT8	DR	—	—	—	—	—	B2	B1	B0
PORT9	DR	—	B6	B5	B4	B3	B2	B1	B0
PORTA	DR	—	—	B5	B4	B3	B2	B1	B0
PORTB	DR	B7	B6	B5	B4	B3	B2	B1	B0
PORTD	DR	B7	B6	B5	B4	B3	B2	B1	B0
PORTE	DR	—	—	B5	B4	B3	—	B1	B0
PORTG	DR	—	—	B5	B4	B3	B2	B1	B0
PORT1	PORT	—	—	—	—	—	—	B1	B0
PORT2	PORT	—	—	—	B4	B3	B2	B1	B0
PORT3	PORT	—	—	—	—	B3	B2	B1	B0
PORT4	PORT	B7	B6	B5	B4	B3	B2	B1	B0
PORT5	PORT	—	—	B5	B4	B3	B2	B1	B0
PORT6	PORT	—	—	B5	B4	B3	B2	B1	B0
PORT7	PORT	—	B6	B5	B4	B3	B2	B1	B0
PORT8	PORT	—	—	—	—	—	B2	B1	B0
PORT9	PORT	—	B6	B5	B4	B3	B2	B1	B0
PORTA	PORT	—	—	B5	B4	B3	B2	B1	B0
PORTB	PORT	B7	B6	B5	B4	B3	B2	B1	B0
PORTD	PORT	B7	B6	B5	B4	B3	B2	B1	B0
PORTE	PORT	—	—	B5	B4	B3	B2	B1	B0
PORTG	PORT	—	—	B5	B4	B3	B2	B1	B0
PORT1	ICR	—	—	—	—	—	—	B1	B0
PORT2	ICR	—	—	—	B4	B3	B2	B1	B0
PORT3	ICR	—	—	—	—	B3	B2	B1	B0
PORT4	ICR	B7	B6	B5	B4	B3	B2	B1	B0
PORT5	ICR	—	—	B5	B4	B3	B2	B1	B0
PORT6	ICR	—	—	B5	B4	B3	B2	B1	B0
PORT7	ICR	—	B6	B5	B4	B3	B2	B1	B0
PORT8	ICR	—	—	—	—	—	B2	B1	B0
PORT9	ICR	—	B6	B5	B4	B3	B2	B1	B0
PORTA	ICR	—	—	B5	B4	B3	B2	B1	B0
PORTB	ICR	B7	B6	B5	B4	B3	B2	B1	B0
PORTD	ICR	B7	B6	B5	B4	B3	B2	B1	B0
PORTE	ICR	—	—	B5	B4	B3	—	B1	B0
PORTG	ICR	—	—	B5	B4	B3	B2	B1	B0
IOPORT	PF8IRQ	—	—	—	—	ITS1[1:0]		ITS0[1:0]	
IOPORT	PF9IRQ	—	—	—	—	—	ITS2	—	—
IOPORT	PFAADC	—	—	—	—	—	—	ADTRG1S	ADTRG0S
IOPORT	PFCMTU	TCLKS[1:0]		—	—	—	—	MTUS1	MTUS0
IOPORT	PFDGPT	—	—	—	—	—	—	—	GPTS
IOPORT	PFFSCI	—	—	—	—	—	SCI2S	—	—
IOPORT	PFGSPI	SSL3E	SSL2E	SSL1E	SSL0E	MISOE	MOSIE	RSPCKE	—
IOPORT	PFHSPI	—	—	—	—	—	—	RSPIS[1:0]	
IOPORT	PFJCAN	CANS[1:0]		—	—	—	—	—	CANE
IOPORT	PFKLIN	—	—	—	—	—	—	—	LINE
IOPORT	PFMPOE	—	—	—	POE11E	POE10E	POE8E	POE4E	POE0E
IOPORT	PFNPOE	POE10S	—	—	—	—	—	—	—
SYSTEM	DPSBYCR	DPSBY	IOKEEP	—	—	—	—	—	—
SYSTEM	DPSWCR	—	—	WTSTS[5:0]					
SYSTEM	DPSIER	DNMIE	—	—	DLVDE	—	—	DIRQ1E	DIRQ0E

Table 4.2 List of I/O Registers (Bit Order) (16 / 30)

Module Abbreviation	Register Abbreviation	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
POE	POECR2	—	—	—	—	—	MTU3BDZE	MTU4ACZE	MTU4BDZE
		—	—	—	—	—	MTU6BDZE	MTU7ACZE	MTU7BDZE
POE	POECR3	—	—	—	—	—	—	GPT3ABZE	GPT2ABZE
		—	—	—	—	—	—	GPT1ABZE	GPT0ABZE
POE	POECR4	—	—	IC5ADDMT67ZE	IC4ADDMT67ZE	IC3ADDMT67ZE	—	IC1ADDMT67ZE	CMADDMT67ZE
		—	—	IC5ADDMT34ZE	IC4ADDMT34ZE	IC3ADDMT34ZE	IC2ADDMT34ZE	—	CMADDMT34ZE
POE	POECR5	—	—	—	—	—	—	—	—
		—	—	IC5ADDMT0ZE	IC4ADDMT0ZE	—	IC2ADDMT0ZE	IC1ADDMT0ZE	CMADDMT0ZE
POE	POECR6	—	—	—	IC4ADDGPT23ZE	IC3ADDGPT23ZE	IC2ADDGPT23ZE	IC1ADDGPT23ZE	CMADDGPT23ZE
		—	—	IC5ADDGPT01ZE	—	IC3ADDGPT01ZE	IC2ADDGPT01ZE	IC1ADDGPT01ZE	CMADDGPT01ZE
POE	ICSR4	—	—	—	POE10F	—	—	POE10E	PIE4
		—	—	—	—	—	—	POE10M[1:0]	
POE	ALR1	—	—	—	—	—	—	—	—
		OLSEN	—	OLSG2B	OLSG2A	OLSG1B	OLSG1A	OLSG0B	OLSG0A
POE	ICSR5	—	—	—	POE11F	—	—	POE11E	PIE5
		—	—	—	—	—	—	POE11M[1:0]	
CAN0*3	MB.ID	IDE	RTR	—			SID[10:0]		
				SID[10:0]				EID[17:0]	
					EID[17:0]				
					EID[17:0]				
	MB.DLC	—	—	—	—	—	—	—	—
		—	—	—	—		DLC[3:0]		
	MB.DATA 0 to 7								
	MB.TS				TSH[7:0]				
					TSL[7:0]				
CAN0*3	MKR0	—	—	—			SID[10:0]		
				SID[10:0]				EID[17 0]	
					EID[17:0]				
					EID[17:0]				
CAN0*3	MKR1	—	—	—			SID[10:0]		
				SID[10:0]				EID[17 0]	
					EID[17:0]				
					EID[17:0]				
CAN0*3	MKR2	—	—	—			SID[10:0]		
				SID[10:0]				EID[17 0]	
					EID[17:0]				
					EID[17:0]				
CAN0*3	MKR3	—	—	—			SID[10:0]		
				SID[10:0]				EID[17 0]	
					EID[17:0]				
					EID[17:0]				
CAN0*3	MKR4	—	—	—			SID[10:0]		
				SID[10:0]				EID[17 0]	
					EID[17:0]				
					EID[17:0]				

Table 4.2 List of I/O Registers (Bit Order) (20 / 30)

Module Abbreviation	Register Abbreviation	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
MTU0	TMDR1	—	BFE	BFB	BFA			MD[3:0]	
MTU0	TIORH		IOB[3:0]					IOA[3:0]	
MTU0	TIORL		IOD[3:0]					IOC[3:0]	
MTU0	TIER	TTEG	—	—	TCIEV	TGIED	TGIEC	TGIEB	TGIEA
MTU0	TSR	—	—	—	TCFV	TGFD	TGFC	TGFB	TGFA
MTU0	TCNT								
MTU0	TGRA								
MTU0	TGRB								
MTU0	TGRC								
MTU0	TGRD								
MTU0	TGRE								
MTU0	TGRF								
MTU0	TIER2	TTGE2	—	—	—	—	—	TGIEF	TGIEE
MTU0	TSR2	—	—	—	—	—	—	TGFF	TGFE
MTU0	TBTM	—	—	—	—	—	TTSE	TTSB	TTSA
MTU1	TCR	—	CCLR[1:0]		CKEG[1:0]			TPSC[2:0]	
MTU1	TMDR1	—	—	—	—			MD[3:0]	
MTU1	TIOR		IOB[3:0]					IOA[3:0]	
MTU1	TIER	TTEG	—	TCIEU	TCIEV	—	—	TGIEB	TGIEA
MTU1	TSR	TCFD	—	TCFU	TCFV	—	—	TGFB	TGFA
MTU1	TCNT								
MTU1	TGRA								
MTU1	TGRB								
MTU1	TICCR	—	—	—	—	I2BE	I2AE	I1BE	I1AE
MTU2	TCR	—	CCLR[1:0]		CKEG[1:0]			TPSC[2:0]	
MTU2	TMDR1	—	—	—	—			MD[3:0]	
MTU2	TIOR		IOB[3:0]					IOA[3:0]	
MTU2	TIER	TTGE	—	TCIEU	TCIEV	—	—	TGIEB	TGIEA
MTU2	TSR	TCFD	—	TCFU	TCFV	—	—	TGFB	TGFA
MTU2	TCNT								
MTU2	TGRA								
MTU2	TGRB								
MTU6	TCR		CCLR[20]		CKEG[1:0]			TPSC[2:0]	
MTU7	TCR		CCLR[20]		CKEG[1:0]			TPSC[2:0]	
MTU6	TMDR1	—	—	BFB	BFA			MD[3:0]	
MTU7	TMDR1	—	—	BFB	BFA			MD[3:0]	
MTU6	TIORH		IOB[3:0]					IOA[3:0]	
MTU6	TIORL		IOD[3:0]					IOC[3:0]	
MTU7	TIORH		IOB[3:0]					IOA[3:0]	

Table 5.2 DC Characteristics (1) (3 / 3)

Note: Items for which test conditions are not specifically stated in the table below have the same values under conditions 1 to 3.

Condition 1: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 3.0 to 3.6 V, VREFH0 = 3.0 V to AVCC0, VREF = 3.0 V to AVCC

Condition 2: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC

Condition 3: VCC = PLLVCC = 4.0 to 5.5 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC
Ta = Topr. Ta is the same under conditions 1 to 3.

Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Input capacitance	All input pins (except for ports PB1 and PB2)	C_{in}	-	-	15	pF	V_{in} = 0 V, f = 1 MHz, T_a = 25°C
	Ports PB1 and PB2		-	-	30		

Note 1. This includes the multiplexed input pins, except in cases where port pins PB1 and PB2 are used as RIIC input pins or port pins P22 to P24, P30, PA3 to PA5, PB0, PD0 to PD2, or PD6 are used as RSPI input pins.

5.3 AC Characteristics

Table 5.6 Operation Frequency Value

Note:Items for which test conditions are not specifically stated in the table below have the same values under conditions 1 to 3.

Condition 1: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 3.0 to 3.6 V, VREFH0 = 3.0 V to AVCC0, VREF = 3.0 V to AVCC

Condition 2: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC

Condition 3: VCC = PLLVCC = 4.0 to 5.5 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC
Ta = Topr. Ta is the same under conditions 1 to 3.

Item		Symbol	Min.	Typ.	Max.	Unit
Operating frequency	System clock (ICLK)	f	8	-	100	MHz
	Peripheral module clock (PCLK)		8	-	50	

5.3.1 Clock Timing

Table 5.7 Clock Timing

Note:Items for which test conditions are not specifically stated in the table below have the same values under conditions 1 to 3.

Condition 1: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 3.0 to 3.6 V, VREFH0 = 3.0 V to AVCC0, VREF = 3.0 V to AVCC
Condition 2: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC
Condition 3: VCC = PLLVCC = 4.0 to 5.5 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC
Ta = Topr. Ta is the same under conditions 1 to 3.

Item	Symbol	Min.	Max.	Unit	Test Conditions
Oscillation settling time after reset (crystal)	t_{OSC1}	10	-	ms	Figure 5.1
Oscillation settling time after leaving software standby mode (crystal)	t_{OSC2}	10	-	ms	Figure 5.2
Oscillation settling time after leaving deep software standby mode (crystal)	t_{OSC3}	10	-	ms	Figure 5.3
EXTAL external clock output delay settling time	t_{DEXT}	1	-	ms	Figure 5.1
EXTAL external clock input low pulse width	t_{EXL}	35	-	ns	Figure 5.4
EXTAL external clock input high pulse width	t_{EXH}	35	-	ns	
EXTAL external clock rising time	t_{EXr}	-	5	ns	
EXTAL external clock falling time	t_{EXf}	-	5	ns	
On-chip oscillator (IWDTCLK) oscillation frequency	$f_{IWDTCLK}$	62.5	187.5	kHz	

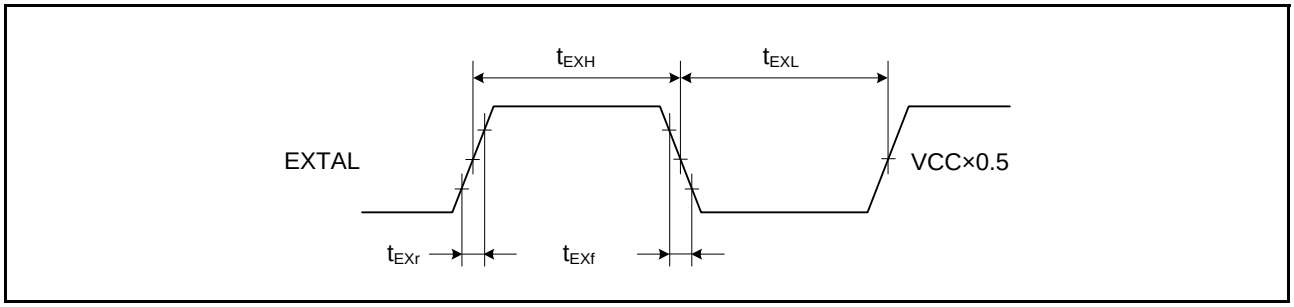


Figure 5.4 EXTAL External Input Clock Timing

Table 5.10 Timing of On-Chip Peripheral Modules (2)

Note:Items for which test conditions are not specifically stated in the table below have the same values under conditions 1 to 3.

Condition 1: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 3.0 to 3.6 V, VREFH0 = 3.0 V to AVCC0, VREF = 3.0 V to AVCC

Condition 2: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC

Condition 3: VCC = PLLVCC = 4.0 to 5.5 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC
Ta = Topr. Ta is the same under conditions 1 to 3.

Item		Symbol	Min.*1 *2	Max.	Unit	Test Conditions
RIIC (standard mode)	SCL input cycle time	t_{SCL}	6(12) × t_{IICcyc} + 1300	-	ns	Figure 5.10
	SCL input high pulse width	t_{SCLH}	3(6) × t_{IICcyc} + 300	-	ns	
	SCL input low pulse width	t_{SCLL}	3(6) × t_{IICcyc} + 1000	-	ns	
	SCL, SDA input rising time	t_{Sr}	-	1000	ns	
	SCL, SDA input falling time	t_{Sf}	-	300	ns	
	SCL, SDA input spike pulse removal time	t_{SP}	0	1(4) × t_{IICcyc}	ns	
	SDA input bus free time	t_{BUF}	3(6) × t_{IICcyc} + 300	-	ns	
	Start condition input hold time	t_{STAH}	t_{IICcyc} + 300	-	ns	
	Re-start condition input setup time	t_{STAS}	1000	-	ns	
	Stop condition input setup time	t_{STOS}	1000	-	ns	
	Data input setup time	t_{SDAS}	t_{IICcyc} + 50	-	ns	
	Data input hold time	t_{SDAH}	0	-	ns	
	SCL, SDA capacitive load	C_b	-	400	pF	
RIIC (fast mode)	SCL input cycle time	t_{SCL}	6(12) × t_{IICcyc} + 600	-	ns	
	SCL input high pulse width	t_{SCLH}	3(6) × t_{IICcyc} + 300	-	ns	
	SCL input low pulse width	t_{SCLL}	3(6) × t_{IICcyc} + 300	-	ns	
	SCL, SDA input rising time	t_{Sr}	20 + 0.1C_b	300	ns	
	SCL, SDA input falling time	t_{Sf}	20 + 0.1C_b	300	ns	
	SCL, SDA input spike pulse removal time	t_{SP}	0	1(4) × t_{IICcyc}	ns	
	SDA input bus free time	t_{BUF}	3(6) × t_{IICcyc} + 300	-	ns	
	Start condition input hold time	t_{STAH}	t_{IICcyc} + 300	-	ns	
	Re-start condition input setup time	t_{STAS}	300	-	ns	
	Stop condition input setup time	t_{STOS}	300	-	ns	
	Data input setup time	t_{SDAS}	t_{IICcyc} + 50	-	ns	
	Data input hold time	t_{SDAH}	0	-	ns	
	SCL, SDA capacitive load	C_b	-	400	pF	

Note: • t_{IICcyc}: Cycles of internal base clock (IICφ) for the RIIC module
Note 1. The value in parentheses is used when ICMR3.NF[1:0] are set to 11b while a digital filter is enabled with ICFER.NFE = 1.
Note 2. Cb indicates the total capacity of the bus line.

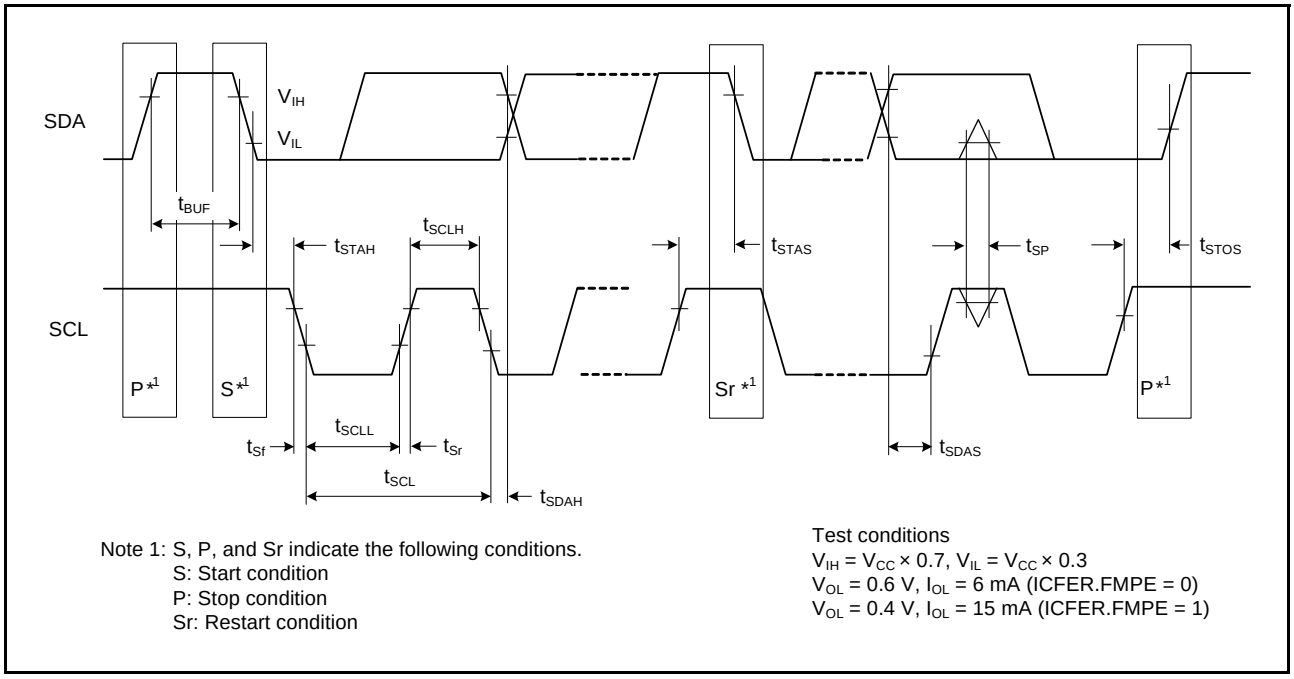


Figure 5.10 I2C Bus Interface Input/Output Timing

5.6 Oscillation Stop Detection Timing

Table 5.20 Oscillation Stop Detection Circuit Characteristics

Note:Items for which test conditions are not specifically stated in the table below have the same values under conditions 1 to 3.

Condition 1: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 3.0 to 3.6 V, VREFH0 = 3.0 V to AVCC0, VREF = 3.0 V to AVCC

Condition 2: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC

Condition 3: VCC = PLLVCC = 4.0 to 5.5 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC
Ta = Topr. Ta is the same under conditions 1 to 3.

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Detection time	tdr	-	-	1.0	ms	Figure 5.23
Internal oscillation frequency when oscillation stop is detected	f_{MAIN}	0.5	-	7.0	MHz	

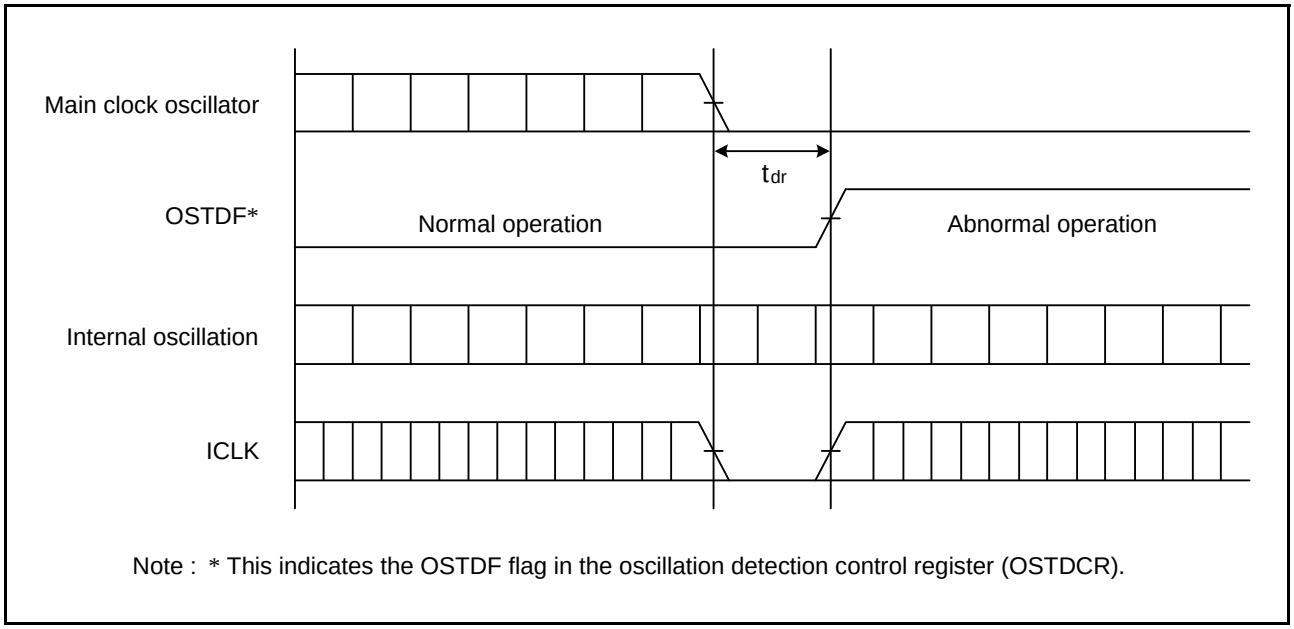


Figure 5.23 Oscillation Stop Detection Timing

5.7 ROM (Flash Memory for Code Storage) Characteristics

Table 5.21 ROM (Flash Memory for Code Storage) Characteristics (1)

Note:Items for which test conditions are not specifically stated in the table below have the same values under conditions 1 to 3.

Condition 1: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 3.0 to 3.6 V, VREFH0 = 3.0 V to AVCC0, VREF = 3.0 V to AVCC

Condition 2: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC

Condition 3: VCC = PLLVCC = 4.0 to 5.5 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC
Temperature range for the programming/erasure operation:
Ta = Topr. Ta is the same under conditions 1 to 3.

Item	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Rewrite/erase cycle*1	N_{PEC}	1000	—	—	Times	
Data hold time	t_{DRP}	30*2	—	—	Year	Ta = +85C°

Note 1. Definition of rewrite/erase cycle:
The rewrite/erase cycle is the number of erasing for each block. When the rewrite/erase cycle is n times (n = 1000), erasing can be performed n times for each block. For instance, when 256-byte writing is performed 16 times for different addresses in 4-Kbyte block and then the entire block is erased, the rewrite/erase cycle is counted as one. However, writing to the same address for several times as one erasing is not enabled (overwriting is prohibited).

Note 2. The value is obtained from the reliability test.

Table 5.22 ROM (Flash Memory for Code Storage) Characteristics (2)

Note:Items for which test conditions are not specifically stated in the table below have the same values under conditions 1 to 3.

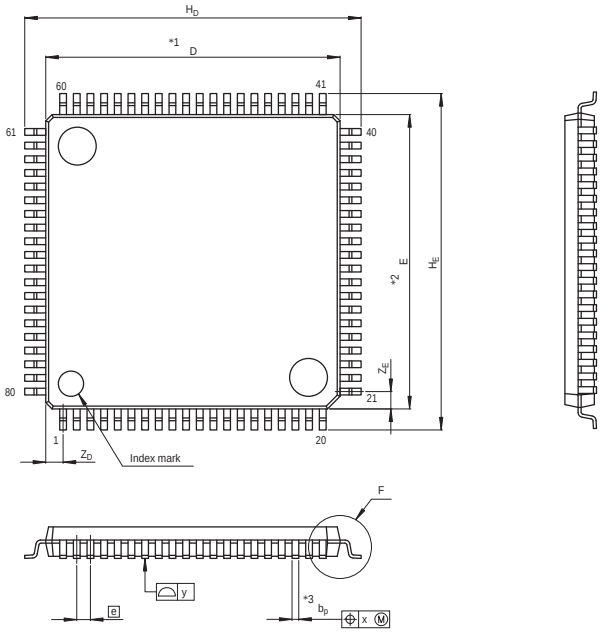
Condition 1: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 3.0 to 3.6 V, VREFH0 = 3.0 V to AVCC0, VREF = 3.0 V to AVCC

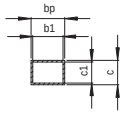
Condition 2: VCC = PLLVCC = 2.7 to 3.6 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC

Condition 3: VCC = PLLVCC = 4.0 to 5.5 V, VSS = PLLVSS = AVSS0 = AVSS = VREFL0 = 0 V
AVCC0 = AVCC = 4.0 to 5.5 V, VREFH0 = 4.0 V to AVCC0, VREF = 4.0 V to AVCC
Temperature range for the programming/erasure operation:
Ta = Topr. Ta is the same under conditions 1 to 3.

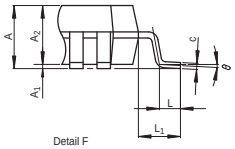
Item		Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Programming time	256 bytes	t_{P256}	—	2	12	ms	PCLK = 50 MHz $N_{PEC} \leq 100$
	4 Kbytes	t_{P4K}	—	23	50	ms	
	16 Kbytes	t_{P16K}	—	90	200	ms	
	256 byte	t_{P256}	—	2.4	14.4	ms	PCLK = 50 MHz $N_{PEC} > 100$
	4 Kbytes	t_{P4K}	—	27.6	60	ms	
	16 Kbytes	t_{P16K}	—	108	240	ms	
Erasure time	4 Kbytes	t_{E4K}	—	25	60	ms	PCLK = 50 MHz $N_{PEC} \leq 100$
	16 Kbytes	t_{E16K}	—	100	240	ms	
	4 Kbytes	t_{E4K}	—	30	72	ms	PCLK = 50 MHz $N_{PEC} > 100$
	16 Kbytes	t_{E16K}	—	120	288	ms	
Suspend delay time during writing		t_{SPD}	—	—	120	µs	Figure 5.24 PCLK = 50 MHz
First suspend delay time during erasing (in suspend priority mode)		t_{SESD1}	—	—	120	µs	
Second suspend delay time during erasing (in suspend priority mode)		t_{SESD2}	—	—	1.7	ms	
Suspend delay time during erasing (in erasure priority mode)		t_{SEED}	—	—	1.7	ms	

JEITA Package Code	RENESAS Code	Previous Code	MASS[Typ.]
P-LQFP80-14x14-0.65	PLQP0080JA-A	FP-80W / FP-80WV	0.6g





Terminal cross section



Detail F

NOTE)
1. DIMENSIONS "*1" AND "*2" DO NOT INCLUDE MOLD FLASH.
2. DIMENSION "*3" DOES NOT INCLUDE TRIM OFFSET.

Reference Symbol	Dimension in Millimeters		
	Min	Nom	Max
D	13.9	14.0	14.1
E	13.9	14.0	14.1
A_2	—	1.4	—
H_D	15.8	16.0	16.2
H_E	15.8	16.0	16.2
A	—	—	1.7
A_1	0.05	0.1	0.15
b_p	0.27	0.32	0.37
b_1	—	0.30	—
c	0.09	0.145	0.20
c_1	—	0.125	—
θ	0°	—	8°
e	—	0.65	—
x	—	—	0.13
y	—	—	0.10
Z_D	—	0.825	—
Z_E	—	0.825	—
L	0.35	0.5	0.65
L_1	—	1.0	—

Figure C 80-Pin LQFP (PLQP0080JA-A) Package Dimensions

General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this document, refer to the relevant sections of the document as well as any technical updates that have been issued for the products.

1. Handling of Unused Pins

   Handle unused pins in accordance with the directions given under Handling of Unused Pins in the manual.

   — The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

2. Processing at Power-on

   The state of the product is undefined at the moment when power is supplied.

   — The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.
   In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed. In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

3. Prohibition of Access to Reserved Addresses

   Access to reserved addresses is prohibited.

   — The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

4. Clock Signals

   After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

   — When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

5. Differences between Products

   Before changing from one product to another, i.e. to a product with a different part number, confirm that the change will not lead to problems.

   — The characteristics of an MPU or MCU in the same group but having a different part number may differ in terms of the internal memory capacity, layout pattern, and other factors, which can affect the ranges of electrical characteristics, such as characteristic values, operating margins, immunity to noise, and amount of radiated noise. When changing to a product with a different part number, implement a system-evaluation test for the given product.

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